TOSHIBA Field Effect Transistor Silicon P Channel MOS Type (U-MOSIII)

SSM6J25FE

High Speed Switching Applications

• Optimum for high-density mounting in small packages

• Low on-resistance: $R_{on} = 260 \text{m}\Omega \text{ (max) (@V_{GS} = -4 V)}$

 $R_{on} = 430 m\Omega \text{ (max) } (@V_{GS} = -2.5 \text{ V})$

www.DataShee'Absolute Maximum Ratings (Ta = 25°C)

Characteristics		Symbol	Rating	Unit	
Drain-Source voltage		V_{DS}	-20	V	
Gate-Source voltage		V _{GSS}	± 12	V	
Drain current	DC	ID	-0.5	Α	
	Pulse	I _{DP}	-1.5		
Drain power dissipation		P _D (Note 1)	500	mW	
Channel temperature		T _{ch}	150	°C	
Storage temperature range		T _{stg}	-55~150	°C	

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings.

Unit: mm

1.6±0.05

1.2±0.05

1.2±0.05

1.2±0.07

1,2,5,6 :Drain
3 :Gate
4 :Source

ES6

JEDEC

JEITA

TOSHIBA

2-2N1A

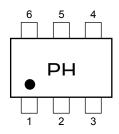
Weight: 3.0 mg (typ.)

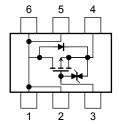
Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/"Derating Concept and Methods") and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

Note 1: Mounted on FR4 board. (25.4 mm \times 25.4 mm \times 1.6 t, Cu Pad: 645 mm 2)

Marking

Equivalent Circuit (top view)





Handling Precaution

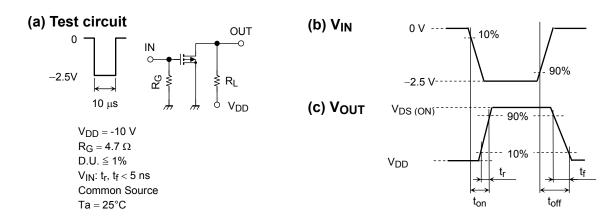
When handling individual devices (which are not yet mounted on a circuit board), be sure that the environment is protected against electrostatic electricity. Operators should wear anti-static clothing, and containers and other objects that come into direct contact with devices should be made of anti-static materials.

Electrical Characteristics (Ta = 25°C)

Chara	cteristics	Symbol	Test Condition	Min	Тур.	Max	Unit	
Gate leakage curr	ent	I _{GSS}	$V_{GS} = \pm 12V, V_{DS} = 0$	_	_	±1	μА	
Drain-Source breakdown voltage		V (BR) DSS	$I_D = -1 \text{ mA}, V_{GS} = 0$	-20	_	_	V	
		V (BR) DSX	$I_D = -1 \text{ mA}, V_{GS} = +12 \text{ V}$	-8	_	_		
Drain cut-off curre	nt	I _{DSS}	$V_{DS} = -20 \text{ V}, V_{GS} = 0$	_	_	-1	μА	
Gate threshold vo	Itage	V_{th}	$V_{DS} = -3 \text{ V}, I_D = -0.1 \text{ mA}$	-0.5	_	-1.1	V	
Forward transfer admittance		Y _{fs}	$V_{DS} = -3 \text{ V}, I_D = -0.25 \text{ A}$ (Note2)	0.65	1.3	_	S	
Drain-Source on-resistance		R _{DS (ON)}	$I_D = -0.25 \text{ A}, V_{GS} = -4 \text{ V}$ (Note2)	_	210	260	mΩ	
			$I_D = -0.25 \text{ A}, V_{GS} = -2.5 \text{ V}$ (Note2)	_	310	430		
Input capacitance C _{iss} V		$V_{DS} = -10 \text{ V}, V_{GS} = 0, f = 1 \text{ MHz}$	_	218	_	pF		
Reverse transfer capacitance		C _{rss}	$V_{DS} = -10 \text{ V}, V_{GS} = 0, f = 1 \text{ MHz}$	_	42	_	pF	
Output capacitance		Coss	V _{DS} = -10 V, V _{GS} = 0, f = 1 MHz	_	52	_	pF	
Switching time	Turn-on time	t _{on}	V _{DD} = -10 V, I _D = -0.25 A,	_	16	_	20	
	Turn-off time	t _{off}	$V_{GS} = 0 \sim -2.5 \text{ V}, R_G = 4.7 \Omega$	_	15	_	ns	

Note2: Pulse test

Switching Time Test Circuit

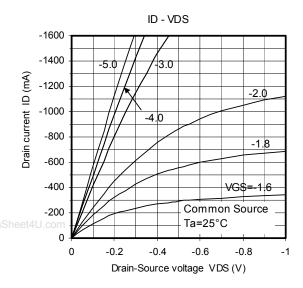


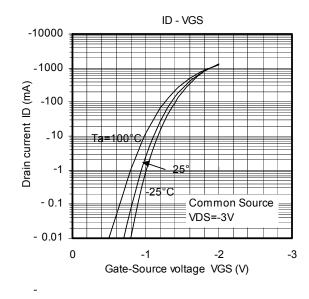
Precaution

 V_{th} can be expressed as the voltage between gate and source when the low operating current value is I_D = _100 μ A for this product. For normal switching operation, $V_{GS\ (on)}$ requires a higher voltage than V_{th} and $V_{GS\ (off)}$ requires a lower voltage than V_{th} .

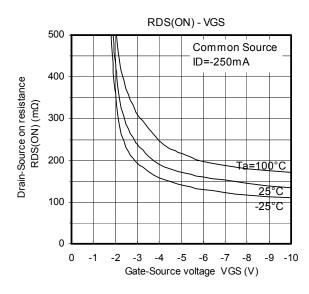
(The relationship can be established as follows: $V_{GS (off)} < V_{th} < V_{GS (on)}$)

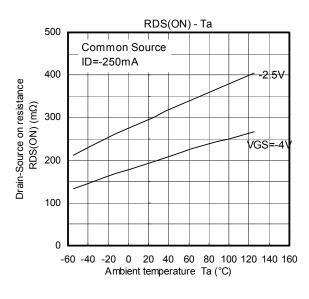
Please take this into consideration when using the device.

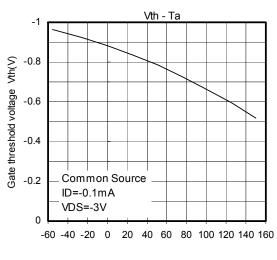


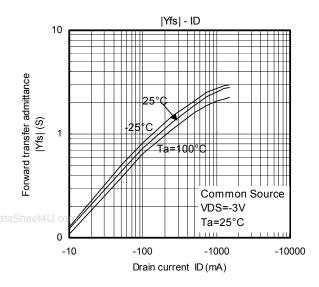


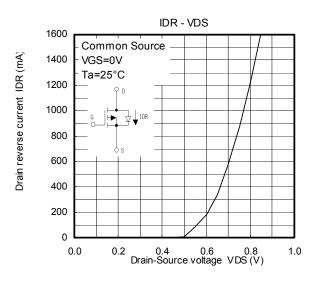
RDS(ON) - ID 500 400 Drain-Source on resistance RDS(ON) (mΩ) -2.5V 300 200 VGS=-4V 100 Common Source Ta=25°C 0 -200 -400 -600 -800 -1000 -1200 -1400 -1600 Drain current ID (mA)

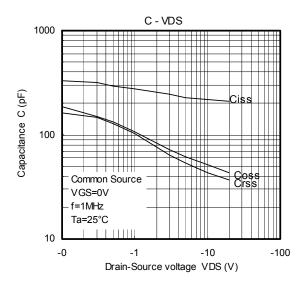


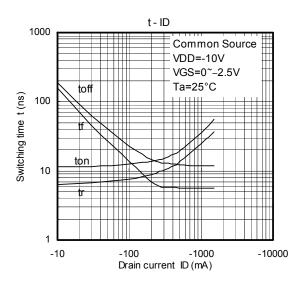


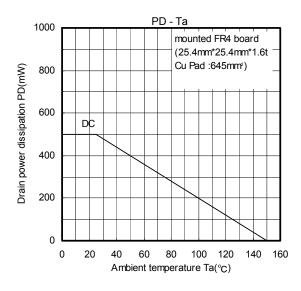












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20070701-EN GENERAL

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